502580929 11/25/2013

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2626968

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
TAO WEN CHUNG	11/22/2011	
CHAN-HONG CHERN	11/22/2011	
MING-CHIEH HUANG	11/22/2011	
CHIH-CHANG LIN	11/22/2011	
YUWEN SWEI	11/22/2011	

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14088521

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: T5057-605A

PATENT

REEL: 031666 FRAME: 0081

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NAME OF SUBMITTER:	RANDY A. NORANBROCK
Signature:	/Randy A. Noranbrock/
Date:	11/25/2013
Total Attachments: 2 source=efiledassgn#page1.tif source=efiledassgn#page2.tif	

PATENT REEL: 031666 FRAME: 0082

2011/11/22 14.55(20 04300)

Docket No. T5057-605

ASSIGNMENT

In consideration of the premises and other good and valuable consideration which is hereby acknowledged, the undersigned,	in hand	paid, the receip	t and sufficiency	of
+ ,,				

- Tao Wen CHUNG
- 4) Chih-Chang LIN
- Chan-Hong CHERN
- 5) Yuwen SWEI
- Ming-Chieh HUANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at

No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

AMPLIFIER INDUCTOR SHARING FOR INDUCTIVE PEAKING

- for which an application for United States Letters Patent was filed on $\frac{2011-12-06}{}$, and identified by United States Patent Application No. $\frac{13/312,228}{}$; or (a)
- (b) for which an application for United States Letters Patent was executed on ____

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

Name: Tao Wea CHUNG

lame: Chan-Hong CHERN

Date:

11/22/201/

Date:

11/22/2011

2011/11/22 (4.58;30 (6839))

Name: Chih-Chagn LIN

Name: Yuwen SWI

11/2

Date:

Date:

PATENT REEL: 031666 FRAME: 0084